

# CLUSTER TOOL SYSTEMS AND METHODS FOR PROCESSING WAFERS

## ABSTRACT OF THE DISCLOSURE

The present invention provides exemplary cluster tool systems and methods for processing wafers, such as semiconductor wafers. One method includes providing a wafer having initial thickness variations between two wafer surfaces. The wafer is processed (Step 216) through a first module (300), with the first module having apparatus for performing a grinding process, a clean process and a metrology process, all preferably within a clean room environment (310). Wafer processing through the first module includes performing the grinding process, clean process and metrology process. The method further includes defining an edge profile on the wafer and processing (Step 222) the wafer through a second module (400).

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